

## General Description

FSMOS<sup>®</sup> MOSFET is based on Oriental Semiconductor's unique device design to achieve low  $R_{DS(ON)}$ , low gate charge, fast switching and excellent avalanche characteristics. The low  $V_{th}$  series is specially optimized for synchronous rectification systems with low driving voltage.

## Features

- Low  $R_{DS(ON)}$  & FOM
- Extremely low switching loss
- Excellent reliability and uniformity
- Fast switching and soft recovery



## Applications

- PD charger
- Motor driver
- Switching voltage regulator
- DC-DC convertor
- Switching mode power supply

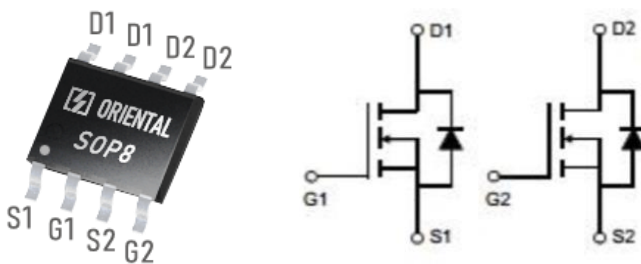
## Key Performance Parameters

Parameter	Value	Unit
$V_{DS, min} @ T_{j(max)}$	100	V
$I_D, pulse$	84	A
$R_{DS(ON), max} @ V_{GS}=10V$	28	m $\Omega$
$Q_g$	11	nC

## Marking Information

Product Name	Package	Marking
SFS10R28BCF	SOP8	SFS10R28BC

## Package & Pin information



**Absolute Maximum Ratings** at  $T_j=25^{\circ}\text{C}$  unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-source voltage	$V_{DS}$	100	V
Gate-source voltage	$V_{GS}$	$\pm 20$	V
Continuous drain current <sup>1)</sup> , $T_C=25^{\circ}\text{C}$	$I_D$	21	A
Pulsed drain current <sup>2)</sup> , $T_C=25^{\circ}\text{C}$	$I_{D, pulse}$	84	A
Continuous diode forward current <sup>1)</sup> , $T_C=25^{\circ}\text{C}$	$I_S$	21	A
Diode pulsed current <sup>2)</sup> , $T_C=25^{\circ}\text{C}$	$I_{S, pulse}$	84	A
Power dissipation <sup>3)</sup> , $T_C=25^{\circ}\text{C}$	$P_D$	27	W
Single pulsed avalanche energy <sup>5)</sup>	$E_{AS}$	8	mJ
Operation and storage temperature	$T_{stg}, T_j$	-55 to 150	$^{\circ}\text{C}$

**Thermal Characteristics**

Parameter	Symbol	Value	Unit
Thermal resistance, junction-case	$R_{\theta JC}$	4.63	$^{\circ}\text{C/W}$
Thermal resistance, junction-ambient <sup>4)</sup>	$R_{\theta JA}$	62	$^{\circ}\text{C/W}$

**Electrical Characteristics** at  $T_j=25^{\circ}\text{C}$  unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	$BV_{DSS}$	100			V	$V_{GS}=0\text{ V}, I_D=250\ \mu\text{A}$
Gate threshold voltage	$V_{GS(th)}$	1.0		2.5	V	$V_{DS}=V_{GS}, I_D=250\ \mu\text{A}$
Drain-source on-state resistance	$R_{DS(ON)}$		23	28	m $\Omega$	$V_{GS}=10\text{ V}, I_D=30\text{ A}$
Drain-source on-state resistance	$R_{DS(ON)}$		27.8	35	m $\Omega$	$V_{GS}=4.5\text{ V}, I_D=30\text{ A}$
Gate-source leakage current	$I_{GSS}$			100	nA	$V_{GS}=20\text{ V}$
				-100		$V_{GS}=-20\text{ V}$
Drain-source leakage current	$I_{DSS}$			1	$\mu\text{A}$	$V_{DS}=100\text{ V}, V_{GS}=0\text{ V}$
Gate resistance	$R_G$		0.8		$\Omega$	$f=1\text{ MHz}, \text{Open drain}$

### Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	$C_{iss}$		688		pF	$V_{GS}=0\text{ V}$ , $V_{DS}=25\text{ V}$ , $f=100\text{ kHz}$
Output capacitance	$C_{oss}$		377		pF	
Reverse transfer capacitance	$C_{rss}$		26		pF	
Turn-on delay time	$t_{d(on)}$		16.8		ns	$V_{GS}=10\text{ V}$ , $V_{DS}=50\text{ V}$ , $R_G=2\ \Omega$ , $I_D=20\text{ A}$
Rise time	$t_r$		3.2		ns	
Turn-off delay time	$t_{d(off)}$		25.4		ns	
Fall time	$t_f$		2		ns	

### Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	$Q_g$		11		nC	$V_{GS}=10\text{ V}$ , $V_{DS}=50\text{ V}$ , $I_D=20\text{ A}$
Gate-source charge	$Q_{gs}$		1.8		nC	
Gate-drain charge	$Q_{gd}$		2.4		nC	
Gate plateau voltage	$V_{plateau}$		3.3		V	

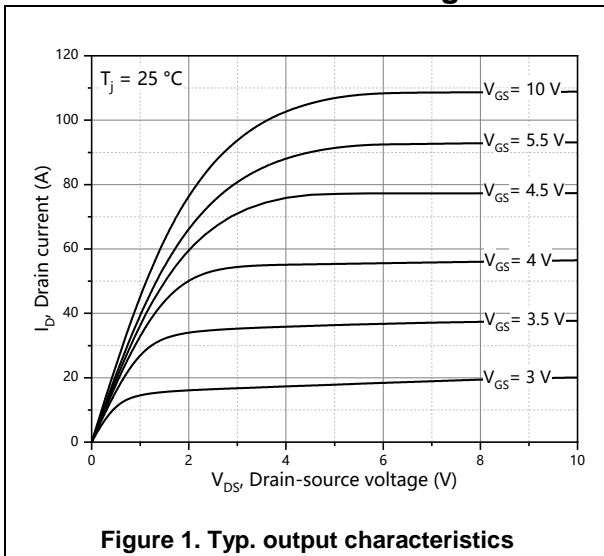
### Body Diode Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Diode forward voltage	$V_{SD}$			1.3	V	$I_S=20\text{ A}$ , $V_{GS}=0\text{ V}$
Reverse recovery time	$t_{rr}$		41.6		ns	$V_R=50\text{ V}$ , $I_S=20\text{ A}$ , $di/dt=100\text{ A}/\mu\text{s}$
Reverse recovery charge	$Q_{rr}$		54.6		nC	
Peak reverse recovery current	$I_{rrm}$		2		A	

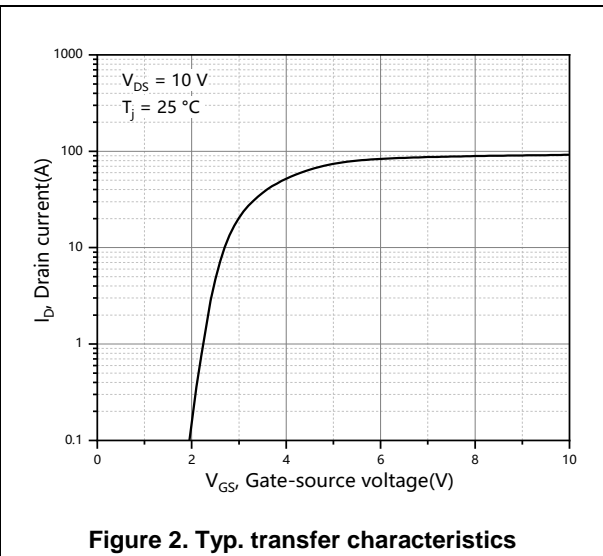
### Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3)  $P_d$  is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_a=25\text{ }^\circ\text{C}$ .
- 5)  $V_{DD}=50\text{ V}$ ,  $V_{GS}=10\text{ V}$ ,  $L=0.3\text{ mH}$ , starting  $T_j=25\text{ }^\circ\text{C}$ .

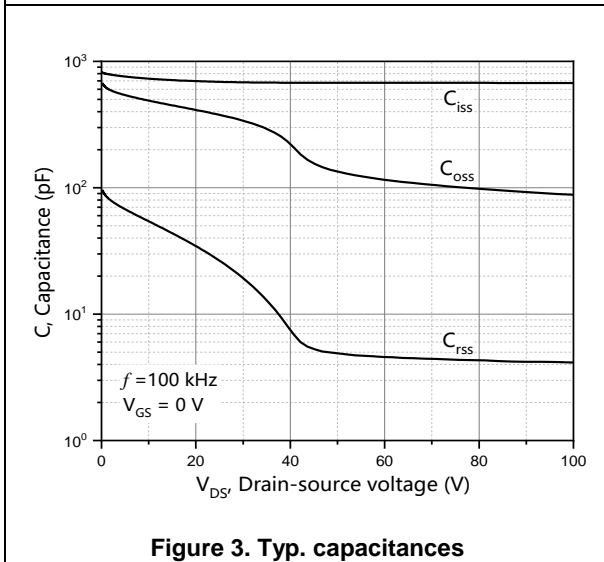
**Electrical Characteristics Diagrams**



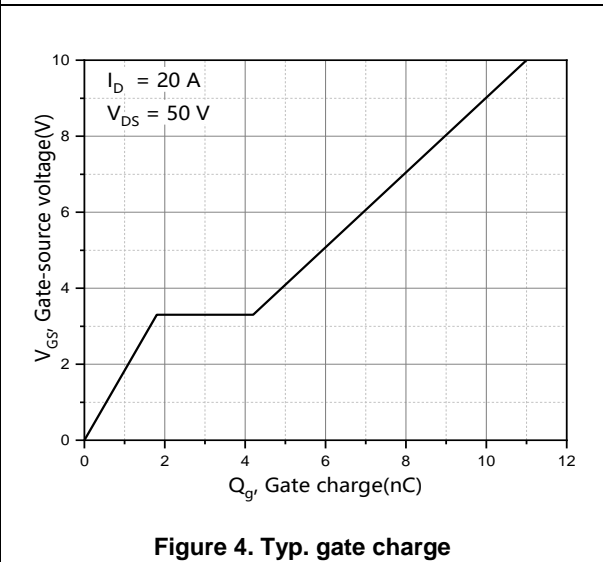
**Figure 1. Typ. output characteristics**



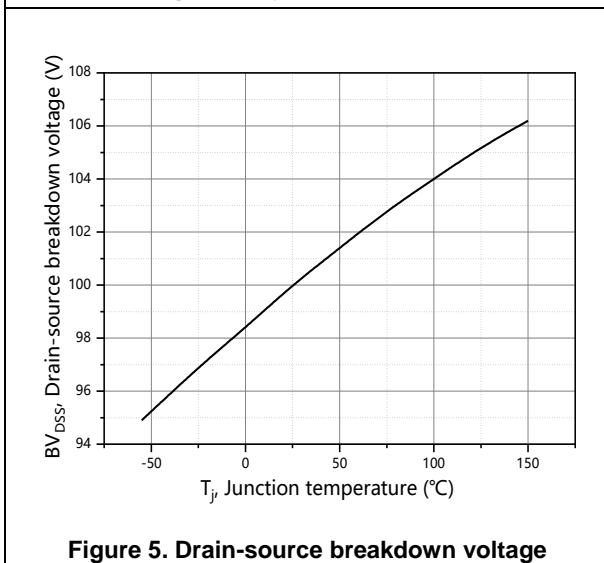
**Figure 2. Typ. transfer characteristics**



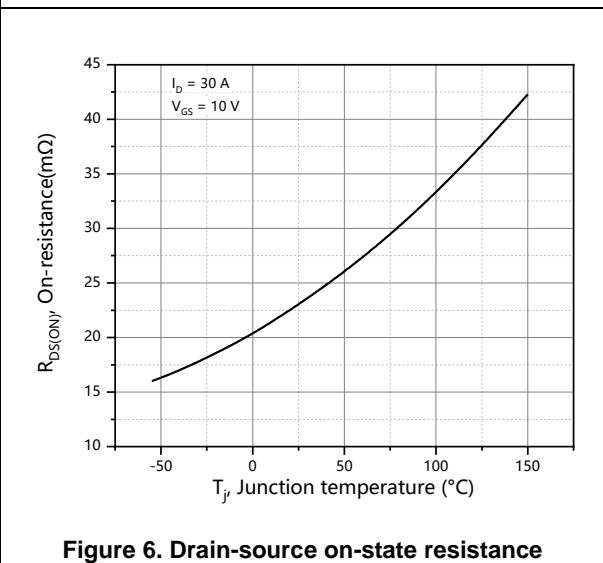
**Figure 3. Typ. capacitances**



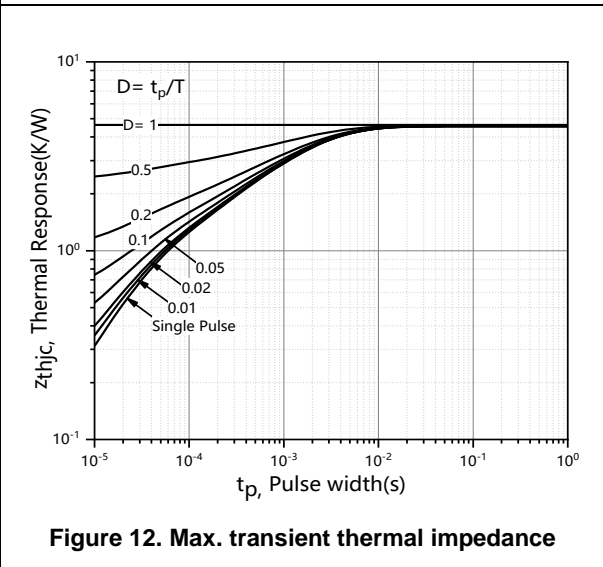
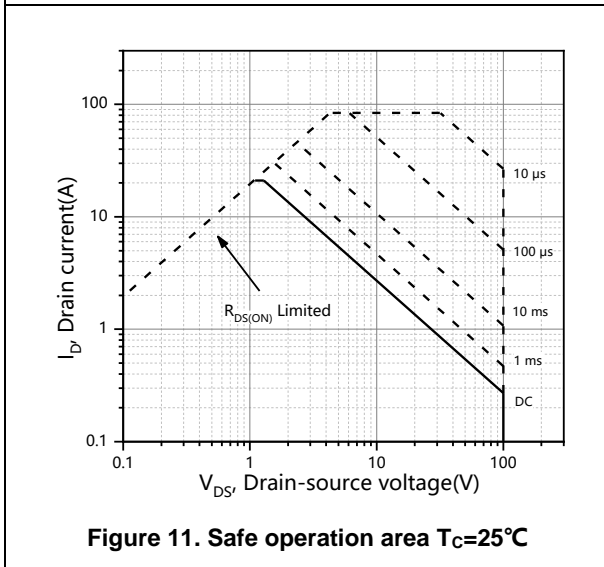
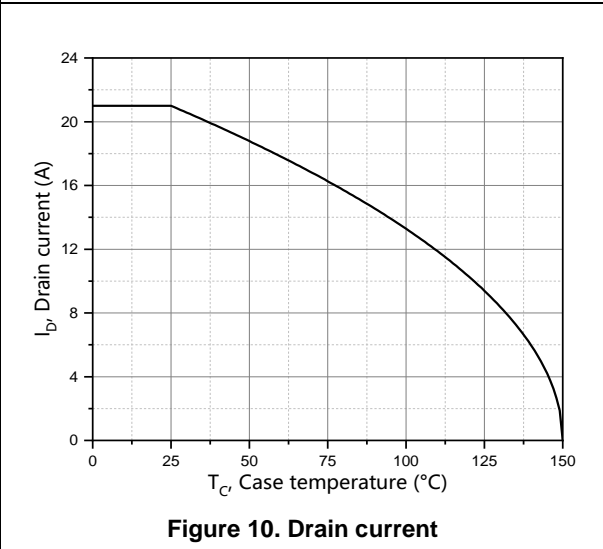
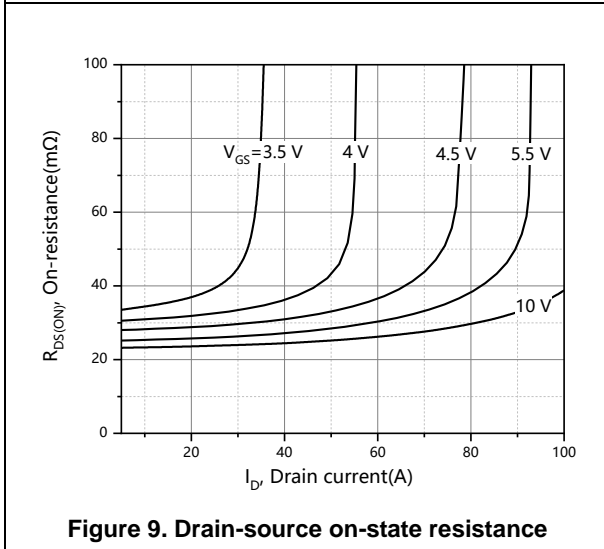
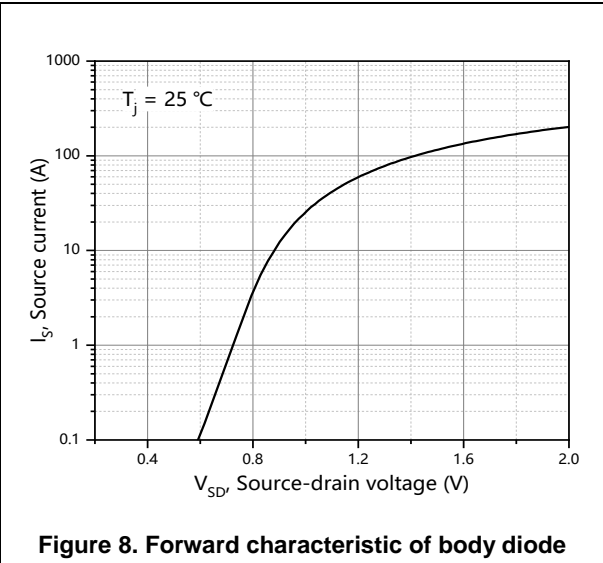
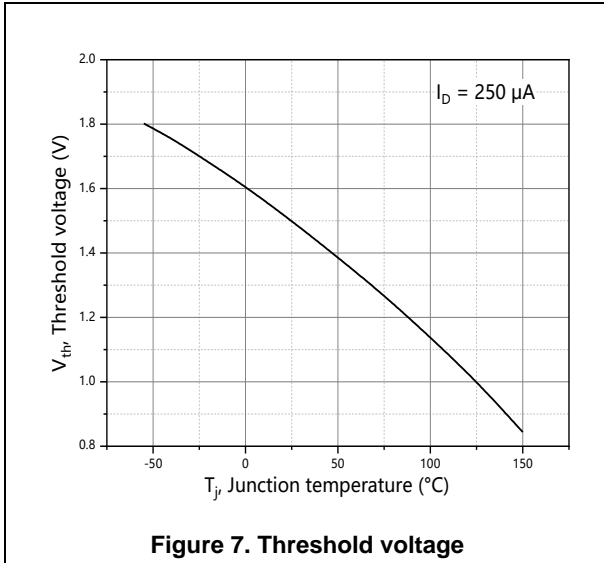
**Figure 4. Typ. gate charge**



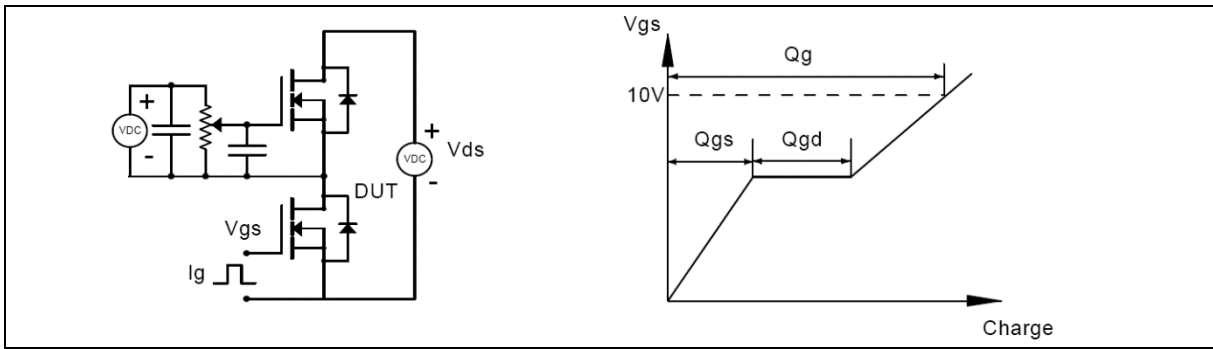
**Figure 5. Drain-source breakdown voltage**



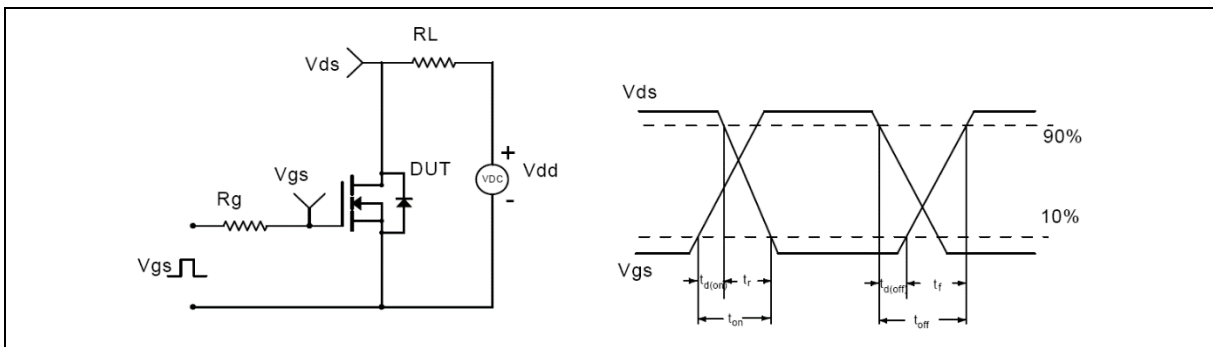
**Figure 6. Drain-source on-state resistance**



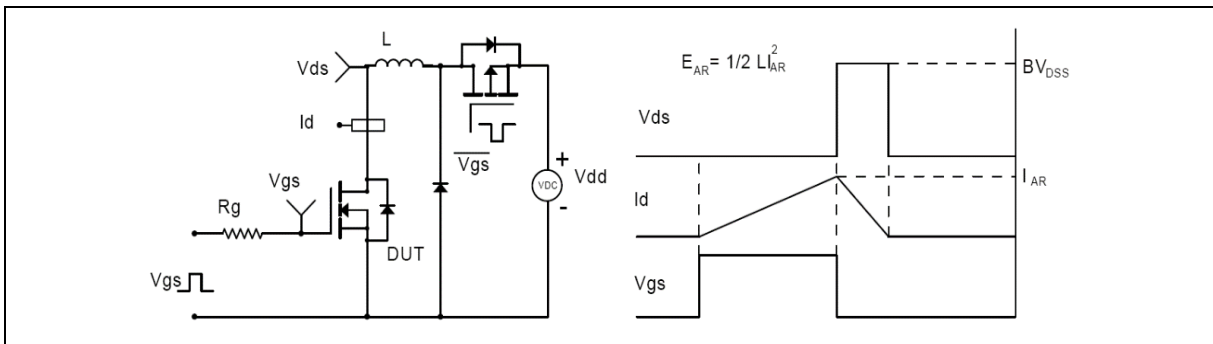
**Test circuits and waveforms**



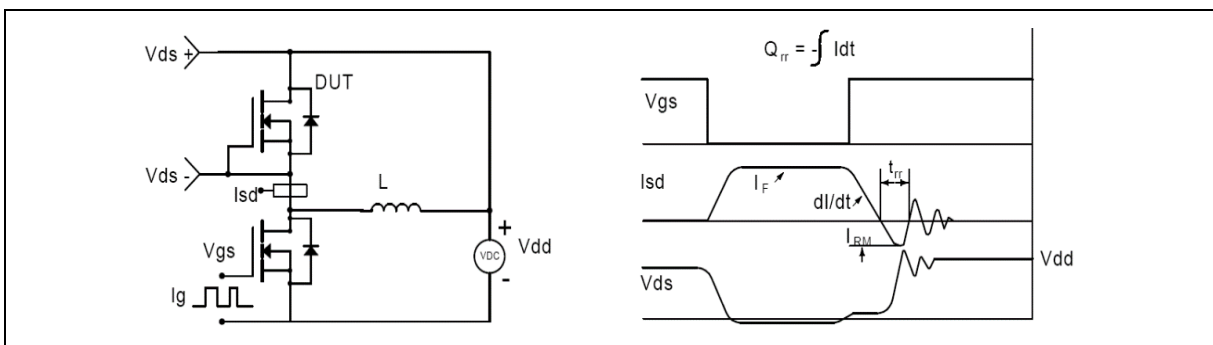
**Figure 1. Gate charge test circuit & waveform**



**Figure 2. Switching time test circuit & waveforms**

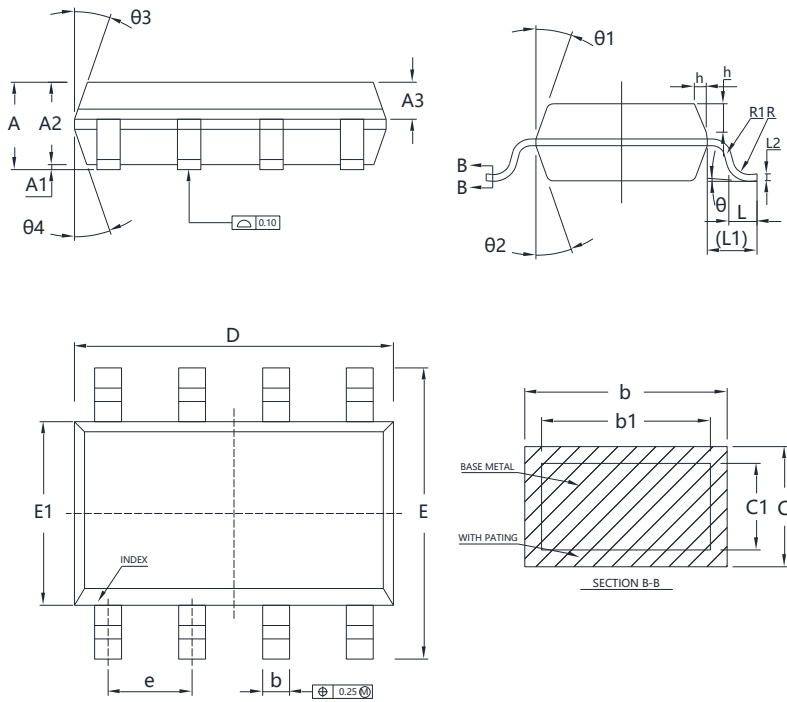


**Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms**



**Figure 4. Diode reverse recovery test circuit & waveforms**

**Package Information**



Symbol	mm		
	Min	Nom	Max
A	1.45	1.55	1.65
A1	0.10	0.15	0.20
A2	1.353	1.40	1.453
A3	0.55	0.60	0.65
b	0.38	-	0.51
b1	0.37	0.42	0.47
c	0.17	-	0.25
c1	0.17	0.20	0.23
D	4.85	4.90	4.95
E	5.85	6.00	6.15
E1	3.85	3.90	3.95
e	1.245	1.270	1.295
h	0.40REF		
θ1-θ4	12° REF		
R	0.15° REF		
R1	0.15° REF		
L	0.45	0.60	0.75
L1	-	1.04 REF	-
L2	-	0.25 BSC	-

Version: SOP8-G package outline dimension

### Ordering Information

Package Type	Units/ Reel	Reels/ Inner Box	Units/ Inner Box	Inner Boxes/ Carton Box	Units/ Carton Box
SOP8-G	4000	2	8000	6	48000

### Product Information

Product	Package	Pb Free	RoHS	Halogen Free
SFS10R28BCF	SOP8	yes	yes	yes

### Legal Disclaimer

The information given in this document shall in no event be regarded as a guarantee of conditions or characteristics. With respect to any examples or hints given herein, any typical values stated herein and/or any information regarding the application of the device, Oriental Semiconductor hereby disclaims any and all warranties and liabilities of any kind, including without limitation, warranties of non-infringement of intellectual property rights of any third party.

For further information on technology, delivery terms and conditions and prices, please contact the Oriental Semiconductor sales representatives ([www.orientalsemi.com](http://www.orientalsemi.com)).

© Oriental Semiconductor Co.,Ltd. All Rights Reserved 



## Revision History

Version	Revision History	Date
V1.0	Initial release	2025-07-11